



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20250508003.2  
Adding TIEM-PR & Clark-PR as additional wafer  
probe test site for Select Devices  
Change Notification / Sample Request**

**Date:** May 09, 2025

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **60** days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **60 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team  
SC Business Services

**20250508003.2**

**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
DRV8889QPWPRQ1	NULL
DRV8262QDDWRQ1	NULL
DRV8899QWRGERQ1	NULL
DRV8889AQPWPRQ1	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	PCN# 20250508003.2			<b>PCN Date:</b>	May 09, 2025																														
<b>Title:</b>	Adding TIEM-PR & Clark-PR as additional wafer probe test site for Select Devices																																		
<b>Customer Contact:</b>		Change Management Team		<b>Dept:</b>	Quality Services																														
<b>Proposed 1<sup>st</sup> Ship Date:</b>		November 05, 2025		<b>Sample requests accepted until:</b>	N/A																														
<b>Change Type:</b> <table border="1"> <tr> <td><input type="checkbox"/></td> <td>Assembly Site</td> <td><input type="checkbox"/></td> <td>Design</td> <td><input type="checkbox"/></td> <td>Wafer Bump Material</td> </tr> <tr> <td><input type="checkbox"/></td> <td>Assembly Process</td> <td><input type="checkbox"/></td> <td>Data Sheet</td> <td><input type="checkbox"/></td> <td>Wafer Bump Process</td> </tr> <tr> <td><input type="checkbox"/></td> <td>Assembly Materials</td> <td><input type="checkbox"/></td> <td>Part number change</td> <td><input type="checkbox"/></td> <td>Wafer Fab Site</td> </tr> <tr> <td><input type="checkbox"/></td> <td>Mechanical Specification</td> <td><input checked="" type="checkbox"/></td> <td>Test Site</td> <td><input type="checkbox"/></td> <td>Wafer Fab Material</td> </tr> <tr> <td><input type="checkbox"/></td> <td>Packing/Shipping/Labeling</td> <td><input type="checkbox"/></td> <td>Test Process</td> <td><input type="checkbox"/></td> <td>Wafer Fab Process</td> </tr> </table>						<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process	<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
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<b>PCN Details</b>																																			
<b>Description of Change:</b> <p>Texas Instruments is pleased to announce TI Philippines as an additional Assembly and Test site for select package devices. No material differences between sites.</p>																																			
<b>Group 1 Device</b> <table border="1"> <thead> <tr> <th></th> <th><b>Current</b></th> <th><b>New</b></th> </tr> </thead> <tbody> <tr> <td>Probe Test site</td> <td>TI CDAT (CD-PR)</td> <td>TI Clark (CLARK-PR)</td> </tr> </tbody> </table>							<b>Current</b>	<b>New</b>	Probe Test site	TI CDAT (CD-PR)	TI Clark (CLARK-PR)																								
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<p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ</p>																																			
<b>Reason for Change:</b> <p>Supply continuity</p>																																			
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b> <p>None</p>																																			
<b>Impact on Environmental Ratings</b> <p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p> <table border="1"> <thead> <tr> <th><b>RoHS</b></th> <th><b>REACH</b></th> <th><b>Green Status</b></th> <th><b>IEC 62474</b></th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>	<input checked="" type="checkbox"/> No Change																									
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<b>Group 1 Product Affected:</b> <p>DRV8262QDDWRQ1</p>																																			
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ZVEI IDs: SEM-TF-01

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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